

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BTS3205G	**Issued**	29. August 2013
MA#	MA001053006		
Package	PG-DSO-8-24	**Weight***	82.84 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.717	0.87	0.87	8655	8655
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		433	
	non noble metal	iron	7439-89-6	0.717	0.87		8658	
	non noble metal	copper	7440-50-8	29.121	35.15	36.07	351543	360742
wire	noble metal	gold	7440-57-5	0.261	0.32	0.32	3155	3155
encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1210	
	plastics	epoxy resin	-	4.612	5.57		55677	
	inorganic material	silicondioxide	60676-86-0	45.420	54.83	60.52	548300	605187
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9824	9824
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7850	7850
glue	plastics	epoxy resin	-	0.066	0.08		803	
	noble metal	silver	7440-22-4	0.313	0.38	0.46	3784	4587
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com